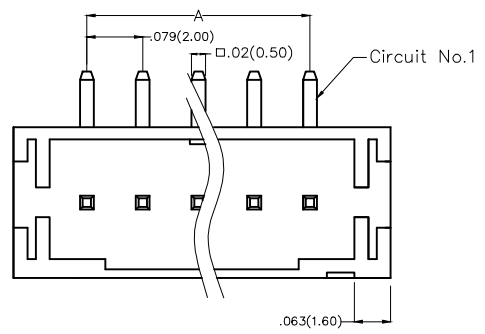
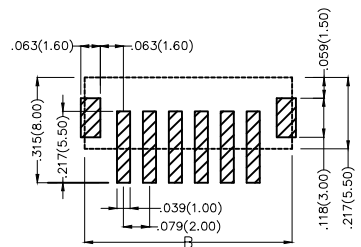
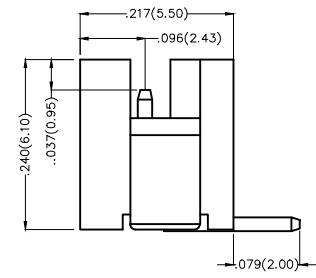
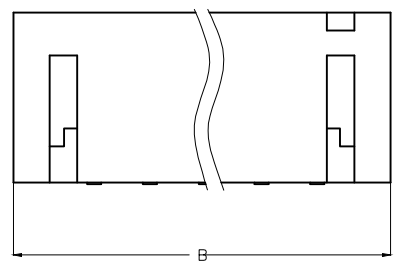


REV	LOCATIONS	DESCRIPTION	DATE	REVISER	APPD
1	△	MPQ 1500Pcs/Reel Change to 1000Pcs/Reel	20150921	CHERRY	FAN
2	△	Change the packing specification	05/MAY/17	KATE	FRANK



**Electrical**  
 Current Rating: 2.0A AC(rms)/DC  
 Voltage Rating: 100V AC(rms)/DC  
 Contact Resistance: 10 mΩ Max  
 Insulation Resistance: 1000 MΩ MIN  
 Withstanding Voltage: 800V AC r.m.s  
 Temperature Range-Operating: -25°C~+85°C

**Material and Plating**  
 Housing: PA9T( UL 94V-0)  
 Contact Pin: Brass  
 Plating: Tin Plated




Recommended P.C.Board Layout

Ordering Information



FWF 200 03 — S XX S 2 4 W5 M  
 1 2 3 4 5 6 7 8 9 10

1	Category	2	Series Number	3	Distinction No.	4	Row Option	5	Circuits	6	Entry Angle
	FWF-Wafer		200-Pitch2.0mm		03		S-Single Row		XX		S-180° Vertical
7	Plating	8	Material-Resin	9	Color-Resin	10	Packaging				
	2-Tin Plated		4-PA9T		W5-White		M-Reel				

THIRD ANGLE PROJECTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		APPROVE BY	DATE	PART NO.		ITEM NO.	 Leader Of Industry
	X.±.012(0.30)	X.±5'	FRANK	18/JUN/13	FWF20003-SXXS24W5M		FWF20003	
DESIGN UNITS Inch (metric)	X.X±.008(0.20)	.X±2'	CHECKED BY	DATE	TITLE			
SCALE 5:1	X.XX±.006(0.15)	.XX±1'	JACOB	18/JUN/13	Wire to Board (Wafer) Pitch 2.0mm 180° Vertical (SMT)			
SIZE A4	X.XXX±.004(0.10)	.XXX±0.5'	DRAWN BY	DATE	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO TXGA INDUSTRIAL ELECTRONICS(S.Z)CO.,LTD AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			
			CHERRY	18/JUN/13	REV 2 SHEET NO. 1/3			

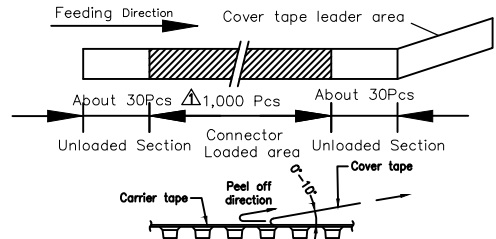
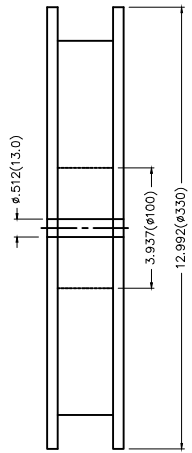
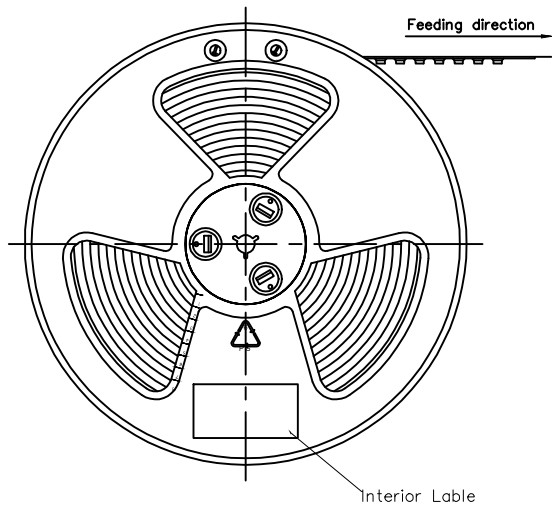
REV	LOCATIONS	DESCRIPTION	DATE	REVISER	APPD
1	△	MPQ 1500Pcs/Reel Change to 1000Pcs/Reel	20150921	CHERRY	FAN
2	△	Change the packing specification	05/MAY/17	KATE	FRANK

Circuits (n)	Part No.	Dimensions(in/mm)	
		A	B
2	FWF20003-S02S24W5M	.079(2.00)	.315(8.00)
3	FWF20003-S03S24W5M	.157(4.00)	.394(10.00)
4	FWF20003-S04S24W5M	.236(6.00)	.472(12.00)
5	FWF20003-S05S24W5M	.315(8.00)	.551(14.00)
6	FWF20003-S06S24W5M	.394(10.00)	.630(16.00)
7	FWF20003-S07S24W5M	.472(12.00)	.709(18.00)
8	FWF20003-S08S24W5M	.551(14.00)	.787(20.00)
9	FWF20003-S09S24W5M	.630(16.00)	.866(22.00)
10	FWF20003-S10S24W5M	.709(18.00)	.945(24.00)
11	FWF20003-S11S24W5M	.787(20.00)	1.024(26.00)
12	FWF20003-S12S24W5M	.866(22.00)	1.102(28.00)
13	FWF20003-S13S24W5M	.945(24.00)	1.181(30.00)

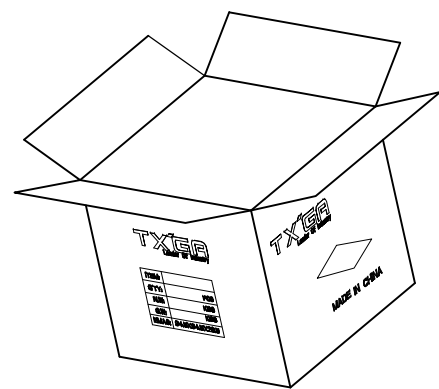
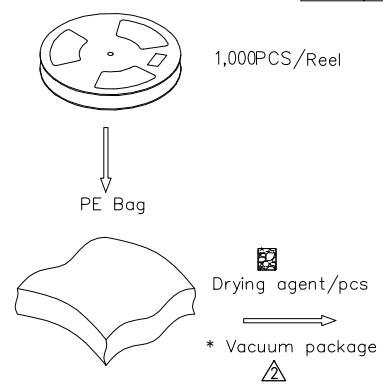
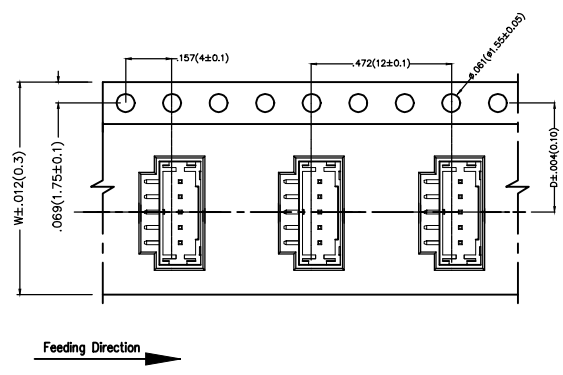
 THIRD ANGLE PROJECTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		APPROVE BY FRANK	DATE 18/JUN/13	PART NO. FWF20003-SXXS24W5M	ITEM NO. FWF20003	 Leader Of Industry	
	DESIGN UNITS Inch (metric)	X.±.012(0.30)	X.±5'	CHECKED BY JACOB	DATE 18/JUN/13	TITLE Wire to Board (Wafer) Pitch 2.0mm 180° Vertical (SMT)		REV 2
SCALE 5:1	SIZE A4	X.XX±.006(0.15)	.XX±1'	DRAWN BY CHERRY	DATE 18/JUN/13	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO TXGA INDUSTRIAL ELECTRONICS(S.Z)CO.,LTD AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		

REV	LOCATIONS	DESCRIPTION	DATE	REVISER	APPD
1	△	MPQ 1500Pcs/Reel Change to 1000Pcs/Reel	20150921	CHERRY	FAN
2	△	Change the packing specification	05/MAY/17	KATE	FRANK

- Note:
- 10 sprocket hole cumulative tolerance±0.2
  - Carrier camber is within 1.0mm in 100mm
  - Material: White Conductive polystyrene Alloy 100% recyclable
  - All dimensions meet EIA-481-3 requirements
  - Component load per 13" reel: 1,000pcs



Circuits (n)	Dimensions(in/mm)		Circuits (n)	Dimensions(in/mm)	
	D	W		D	W
2	.295(7.50)	.630(16.00)	9	.559(14.20)	1.260(32.00)
3	.295(7.50)	.630(16.00)	10	.559(14.20)	1.260(32.00)
4	.453(11.50)	.945(24.00)	11	.795(20.20)	1.732(44.00)
5	.453(11.50)	.945(24.00)	12	.795(20.20)	1.732(44.00)
6	.453(11.50)	.945(24.00)	13	.795(20.20)	1.732(44.00)
7	.559(14.20)	1.260(32.00)			
8	.559(14.20)	1.260(32.00)			



 THIRD ANGLE PROJECTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		APPROVE BY	DATE	PART NO.	ITEM NO.	 Leader Of Industry
	X.±.012(0.30)	X.±5'	FRANK	18/JUN/13	FWF20003-SXXS24W5M	FWF20003	
DESIGN UNITS Inch (metric)	X.XX±.008(0.20)	.X'±2'	CHECKED BY	DATE	TITLE		REV 2
SCALE	X.XX±.006(0.15)	.XX'±1'	JACOB	18/JUN/13	Wire to Board (Wafer) Pitch 2.0mm 180° Vertical (SMT)		
SIZE	X.XXX±.004(0.10)	.XXX'±0.5'	DRAWN BY	DATE	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO TXGA INDUSTRIAL ELECTRONICS(S.Z)CO.,LTD AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		
5:1	A4		CHERRY	18/JUN/13			